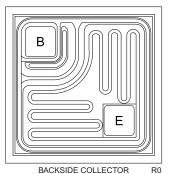


CP327V-CZTA27

NPN - Darlington Transistor Die 0.5 Amp, 60 Volt

The CP327V-CZTA27 die is a silicon NPN Darlington power transistor designed for high gain amplifier applications.



MECHANICAL SPECIFICATIONS:

22.8 x 22.8 MILS
7.1 MILS
4.7 x 4.7 MILS
4.7 x 4.7 MILS
Al-Si – 17,000Å
Au – 9,000Å
1.8 MILS
5 INCHES
33,085

MAXIMUM RATINGS: (T _A =25°C)	SYMBOL		UNITS
Collector-Emitter Voltage	V _{CES}	60	V
Emitter-Base Voltage	V_{EBO}	10	V
Continuous Collector Current	IC	0.5	Α
Operating and Storage Junction Temperature	Ti Tota	-65 to +150	°C

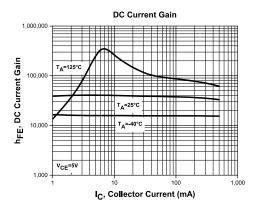
		o, oig				
ELECTRICAL CHARACTERISTICS : (T _A =25°C unless otherwise noted)						
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS		
I _{CBO}	V _{CB} =50V		100	nA		
I _{CES}	V _{CE} =50V		500	nA		
^I EBO	V _{EB} =10V		100	nA		
BV _{CBO}	I _C =100μA	60		V		
BVCES	I _C =100μA	60		V		
V _{CE(SAT)}	I _C =100mA, I _B =0.1mA		1.5	V		
V _{BE(ON)}	V_{CE} =5.0V, I_{C} =100mA		2.0	V		
hFE	V_{CE} =5.0V, I_{C} =10mA	10K				
h _{FE}	V_{CE} =5.0V, I_{C} =100mA	10K				
f_{T}	V_{CE} =5.0V, I_{C} =10mA, f=100MHz	125		MHz		

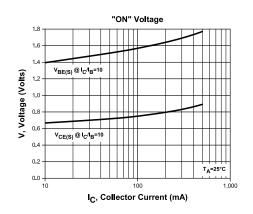
CP327V-CZTA27

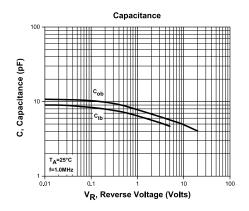
Typical Electrical Characteristics

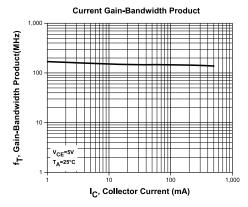


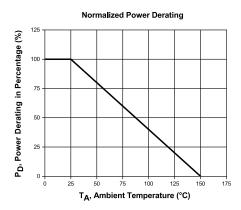
www.centralsemi.com





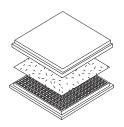






BARE DIE PACKING OPTIONS

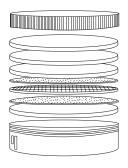




BARE DIE IN TRAY (WAFFLE) PACK

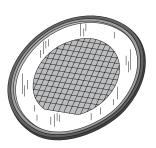
CT: Singulated die in tray (waffle) pack. (example: CP211-PART NUMBER-CT)

CM: Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes). (example: CP211-PART NUMBER-CM)



UNSAWN WAFER

WN: Full wafer, unsawn, 100% tested with reject die inked. (example: CP211-PART NUMBER-WN)



SAWN WAFER ON PLASTIC RING

WR: Full wafer, sawn and mounted on plastic ring,

100% tested with reject die inked. (example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS) is possible as a special order. Please contact your Central Sales Representative at 631-435-1110.



Visit the Central website for a complete listing of specifications: www.centralsemi.com/bdspecs

R2 (3-April 2017)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- · Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

Central Semiconductor Corp. 145 Adams Avenue Hauppauge, NY 11788 USA

Main Tel: (631) 435-1110 Main Fax: (631) 435-1824

Support Team Fax: (631) 435-3388

www.centralsemi.com

Worldwide Field Representatives: www.centralsemi.com/wwreps

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